

24C01SC/02SC

1K/2K 5.0V I²C Serial EEPROMs for Smart Cards

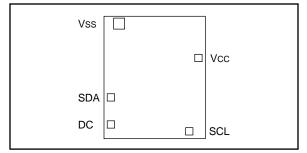
FEATURES

- ISO Standard 7816 pad locations
- Low power CMOS technology
- 1 mA active current typical
- 10 μA standby current typical at 5.5V
- Organized as a single block of 128 bytes (128 x 8) or 256 bytes (256 x 8)
- Two-wire serial interface bus, I²C[™] compatible
- 100 kHz and 400 kHz compatibility
- Self-timed write cycle (including auto-erase)
- Page-write buffer for up to 8 bytes
- 2 ms typical write cycle time for page-write
- ESD protection > 4 kV
- 1,000,000 E/W cycles guaranteed
- Data retention > 200 years
- Available for extended temperature ranges
- Commercial (C): 0°C to +70°C

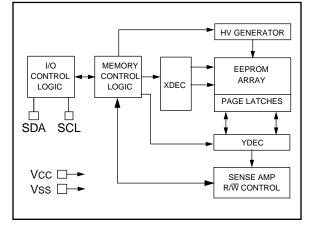
DESCRIPTION

The Microchip Technology Inc. 24C01SC and 24C02SC are 1K-bit and 2K-bit Electrically Erasable PROMs with bondpad positions optimized for smart card applications. The devices are organized as a single block of 128 x 8-bit or 256 x 8-bit memory with a two-wire serial interface. The 24C01SC and 24C02SC also have page-write capability for up to 8 bytes of data.

DIE LAYOUT



BLOCK DIAGRAM



I²C is a trademark of Philips Corporation.

1.0 ELECTRICAL CHARACTERISTICS

Maximum Ratings*

Vcc
All inputs and outputs w.r.t. Vss0.6V to Vcc +1.0V
Storage temperature65°C to +150°C
Ambient temp. with power applied65°C to +125°C
ESD protection on all pads≥4 kV

*Notice: Stresses above those listed under "Maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: PAD FUNCTION TABLE

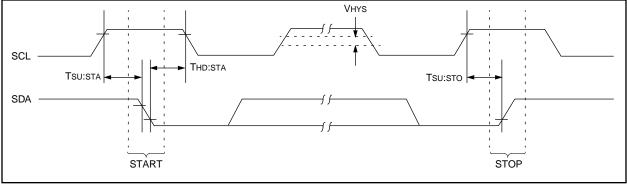
Name	Function
Vss	Ground
SDA	Serial Address/Data I/O
SCL	Serial Clock
Vcc	+4.5V to 5.5V Power Supply
DC	Don't connect

TABLE 1-2: DC CHARACTERISTICS

	VCC = +4.5V to +5.5V		Commercial (C): Tamb =		C): Tamb = $0^{\circ}C$ to $+70^{\circ}C$
Parameter	Symbol	Min.	Max.	Units	Conditions
SCL and SDA pads: High level input voltage	Vін	.7 Vcc	_	_	
Low level input voltage	VIL	—	.3 Vcc	V	
Hysteresis of Schmidt trigger inputs	VHYS	.05 Vcc	_	V	(Note)
Low level output voltage	Vol	—	.40	V	IOL = 3.0 mA, VCC = 4.5V
Input leakage current (SCL)	ILI	-10	10	μA	VIN = .1V to 5.5V
Output leakage current (SDA)	Ilo	-10	10	μA	VOUT = .1V to 5.5V
Pin capacitance (all inputs/outputs)	Cin, Cout	_	10	pF	Vcc = 5.0V (Note 1) Tamb = 25°С, FcLк = 1 MHz
Operating current	Icc Write	_	3	mA	Vcc = 5.5V
	ICC Read		1	mA	Vcc = 5.5V, SCL = 400 KHz
Standby current	lccs		100	μΑ	VCC = 5.5V, SDA = SCL = VCC

Note: This parameter is periodically sampled and not 100% tested.

FIGURE 1-1: BUS TIMING START/STOP



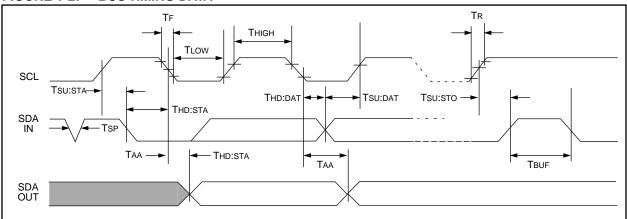
Parameter	Symbol	Min.	Max.	Units	Remarks
Clock frequency	FCLK	—	400	kHz	
Clock high time	Тнідн	600	—	ns	
Clock low time	TLOW	1300	—	ns	
SDA and SCL rise time	TR	—	300	ns	(Note 1)
SDA and SCL fall time	TF	—	300	ns	(Note 1)
START condition hold time	THD:STA	600	_	ns	After this period the first clock pulse is generated
START condition setup time	TSU:STA	600	_	ns	Only relevant for repeated START condition
Data input hold time	THD:DAT	0	_	ns	(Note 2)
Data input setup time	TSU:DAT	100	—	ns	
STOP condition setup time	Tsu:sto	600	—	ns	
Output valid from clock	ΤΑΑ	—	900	ns	(Note 2)
Bus free time	TBUF	1300		ns	Time the bus must be free before a new transmission can start
Output fall time from VIH minimum to VIL maximum	TOF	20 +0.1 CB	250	ns	(Note 1), CB ≤ 100 pF
Input filter spike suppression (SDA and SCL pins)	TSP	_	50	ns	(Note 3)
Write cycle time	Twr	—	10	ms	Byte or Page mode
Endurance	_	10 ⁶	_	cycles	25°C, Vcc = 5V, Block Mode (Note 4)

Note 1: Not 100% tested. CB = total capacitance of one bus line in pF.

2: As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

- 3: The combined TSP and VHYS specifications are due to new Schmitt trigger inputs which provide improved noise spike suppression. This eliminates the need for a TI specification for standard operation.
- 4: This parameter is not tested but guaranteed by characterization. For endurance estimates in a specific application, please consult the Total Endurance Model which can be obtained on our BBS or website.





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2.0 FUNCTIONAL DESCRIPTION

The 24C01SC/02SC supports a bi-directional two-wire bus and data transmission protocol. A device that sends data onto the bus is defined as transmitter, and a device receiving data as receiver. The bus has to be controlled by a master device which generates the serial clock (SCL), controls the bus access, and generates the START and STOP conditions, while the 24C01SC/02SC works as slave. Both master and slave can operate as transmitter or receiver, but the master device determines which mode is activated.

3.0 BUS CHARACTERISTICS

The following bus protocol has been defined:

- Data transfer may be initiated only when the bus is not busy.
- During data transfer, the data line must remain stable whenever the clock line is HIGH. Changes in the data line while the clock line is HIGH will be interpreted as a START or STOP condition.

Accordingly, the following bus conditions have been defined (Figure 3-1).

3.1 Bus not Busy (A)

Both data and clock lines remain HIGH.

3.2 Start Data Transfer (B)

A HIGH to LOW transition of the SDA line while the clock (SCL) is HIGH determines a START condition. All commands must be preceded by a START condition.

3.3 Stop Data Transfer (C)

A LOW to HIGH transition of the SDA line while the clock (SCL) is HIGH determines a STOP condition. All operations must be ended with a STOP condition.

3.4 Data Valid (D)

The state of the data line represents valid data when, after a START condition, the data line is stable for the duration of the HIGH period of the clock signal.

The data on the line must be changed during the LOW period of the clock signal. There is one clock pulse per bit of data.

Each data transfer is initiated with a START condition and terminated with a STOP condition. The number of the data bytes transferred between the START and STOP conditions is determined by the master device and is theoretically unlimited, although only the last 16 will be stored when doing a write operation. When an overwrite does occur, it will replace data in a first in first out fashion.

3.5 Acknowledge

Each receiving device, when addressed, is obliged to generate an acknowledge after the reception of each byte. The master device must generate an extra clock pulse which is associated with this acknowledge bit.

Note:	The 24C01SC/02SC does not generate					
	any acknowledge bits if an internal pro-					
	gramming cycle is in progress.					

The device that acknowledges has to pull down the SDA line during the acknowledge clock pulse in such a way that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse. Of course, setup and hold times must be taken into account. A master must signal an end of data to the slave by not generating an acknowledge bit on the last byte that has been clocked out of the slave. In this case, the slave must leave the data line HIGH to enable the master to generate the STOP condition.

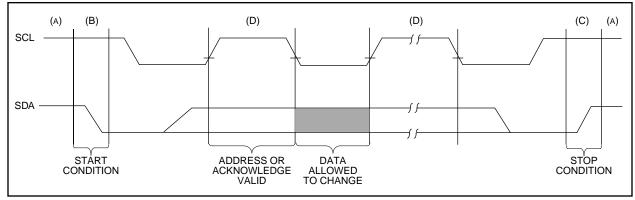


FIGURE 3-1: DATA TRANSFER SEQUENCE ON THE SERIAL BUS

4.0 BUS CHARACTERISTICS

4.1 Slave Address

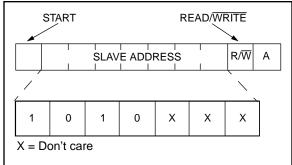
After generating a START condition, the bus master transmits the slave address consisting of a 4-bit device code (1010) for the 24C01SC/02SC, followed by three don't care bits.

The eighth bit of slave address determines if the master device wants to read or write to the 24C01SC/02SC (Figure 4-1).

The 24C01SC/02SC monitors the bus for its corresponding slave address all the time. It generates an acknowledge bit if the slave address was true, and it is not in a programming mode.

Operation	Control Code	Chip Select	R/W
Read	1010	XXX	1
Write	1010	XXX	0

FIGURE 4-1: CONTROL BYTE ALLOCATION



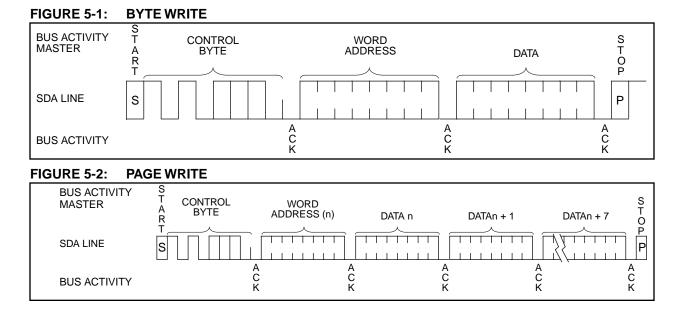
5.0 WRITE OPERATION

5.1 Byte Write

Following the start signal from the master, the device code (4 bits), the don't care bits (3 bits), and the R/Wbit, which is a logic low, is placed onto the bus by the master transmitter. This indicates to the addressed slave receiver that a byte with a word address will follow after it has generated an acknowledge bit during the ninth clock cycle. Therefore, the next byte transmitted by the master is the word address and will be written into the address pointer of the 24C01SC/02SC. After receiving another acknowledge signal from the 24C01SC/02SC, the master device will transmit the data word to be written into the addressed memory location. The 24C01SC/02SC acknowledges again and the master generates a stop condition. This initiates the internal write cycle, and during this time the 24C01SC/02SC will not generate acknowledge signals (Figure 5-1).

5.2 Page Write

The write control byte, word address, and the first data byte are transmitted to the 24C01SC/02SC in the same way as in a byte write. But instead of generating a stop condition, the master transmits up to eight data bytes to the 24C01SC/02SC, which are temporarily stored in the on-chip page buffer and will be written into the memory after the master has transmitted a stop condition. After the receipt of each word, the three lower order address pointer bits are internally incremented by one. The higher order five bits of the word address remains constant. If the master should transmit more than eight words prior to generating the stop condition. the address counter will roll over and the previously received data will be overwritten. As with the byte write operation, once the stop condition is received an internal write cycle will begin (Figure 5-2).

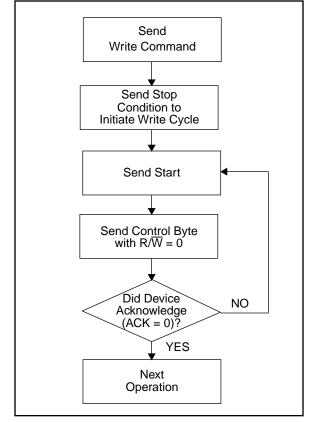


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6.0 ACKNOWLEDGE POLLING

Since the device will not acknowledge during a write cycle, this can be used to determine when the cycle is complete (this feature can be used to maximize bus throughput). Once the stop condition for a write command has been issued from the master, the device initiates the internally timed write cycle. ACK polling can be initiated immediately. This involves the master sending a start condition followed by the control byte for a write command (R/W = 0). If the device is still busy with the write cycle, then NO ACK will be returned. If the cycle is complete, then the device will return the ACK, and the master can then proceed with the next read or write command. See Figure 6-1 for flow diagram.

FIGURE 6-1: ACKNOWLEDGE POLLING FLOW



7.0 READ OPERATION

Read operations are initiated in the same way as write operations with the exception that the R/\overline{W} bit of the slave address is set to one. There are three basic types of read operations: current address read, random read, and sequential read.

7.1 Current Address Read

The 24C01SC/02SC contains an address counter that maintains the address of the last word accessed, internally incremented by one. Therefore, if the previous access (either a read or write operation) was to address n, the next current address read operation would access data from address n + 1. Upon receipt of the slave address with R/W bit set to one, the 24C01SC/02SC issues an acknowledge and transmits the 8-bit data word. The master will not acknowledge the transfer but does generate a stop condition and the 24C01SC/02SC discontinues transmission (Figure 8-2).

7.2 Random Read

Random read operations allow the master to access any memory location in a random manner. To perform this type of read operation, first the word address must be set. This is done by sending the word address to the 24C01SC/02SC as part of a write operation. After the word address is sent, the master generates a start condition following the acknowledge. This terminates the write operation, but not before the internal address pointer is set. Then, the master issues the control byte again but with the R/W bit set to a one. The 24C01SC/02SC will then issue an acknowledge and transmits the 8-bit data word. The master will not acknowledge the transfer but does generate a stop condition and the 24C01SC/02SC discontinues transmission (Figure 8-3).

7.3 Sequential Read

Sequential reads are initiated in the same way as a random read except that after the 24C01SC/02SC transmits the first data byte, the master issues an acknowledge as opposed to a stop condition in a random read. This directs the 24C01SC/02SC to transmit the next sequentially addressed 8-bit word (Figure 9-1).

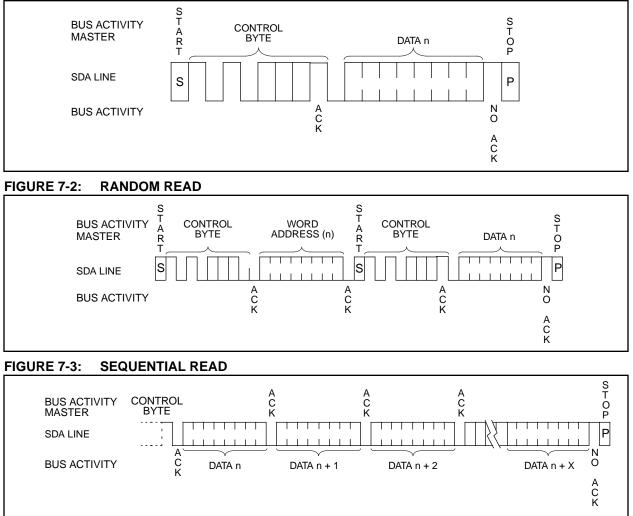
To provide sequential reads the 24C01SC/02SC contains an internal address pointer which is incremented by one at the completion of each operation. This address pointer allows the entire memory contents to be serially read during one operation.

7.4 Noise Protection

The 24C01SC/02SC employs a Vcc threshold detector circuit which disables the internal erase/write logic if the Vcc is below 1.5 volts at nominal conditions.

The SCL and SDA inputs have Schmitt trigger and filter circuits which suppress noise spikes to assure proper device operation even on a noisy bus.





8.0 PAD DESCRIPTIONS

8.1 SDA Serial Address/Data Input/Output

This is a bi-directional pad used to transfer addresses and data into and data out of the device. It is an open drain terminal, therefore the SDA bus requires a pull-up resistor to Vcc (typical $10K\Omega$ for 100 kHz, $1K\Omega$ for 400kHz).

For normal data transfer SDA is allowed to change only during SCL low. Changes during SCL high are reserved for indicating the START and STOP conditions.

8.2 SCL Serial Clock

This input is used to synchronize the data transfer from and to the device.

8.3 DC Don't Connect

This pad is used for test purposes and should not be bonded out. It will be pulled to Vss through an internal resistor.

9.0 DIE CHARACTERISTICS

Figure 9-1 shows the die layout of the 24C01SC/02SC, including bondpad positions. Table 9-1 shows the actual coordinates of the bondpad midpoints with respect to the center of the die.

FIGURE 9-1: DIE LAYOUT

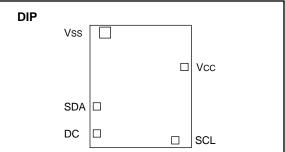


TABLE 9-1:BONDPAD COORDINATES

Pad Name	Pad Midpoint, X dir.	Pad Midpoint, Y dir.
Vss	-495.000	749.130
SDA	-605.875	-271.875
SCL	479.875	-746.625
Vcc	605.875	-261.375

Note 1: Dimensions are in microns.

2: Center of die is at the 0,0 point.

NOTES:

24C01SC/02SC

NOTES:

24C01SC/02SC Product Identification System

To order or to obtain information (e.g., on pricing or delivery), please use the listed part numbers, and refer to the factory or the listed sales offices.

$\frac{24C01SC/02SC}{24C01SC/02SC} - \frac{5}{2} \frac{XX}{2}$	/s xx	Die Thickness -	Blank = 11 mils 08 = 8 mils Other die thicknesses available, please consult factory.	
			Package: -	S = Die in Wafer Pak W = Wafer WF = Sawed Wafer on Frame
			Temperature Range:	Blank = 0°C to +70°C
			Device:	24C01SC1K 1²C ISO Smart Card die24C02SC2K 1²C ISO Smart Card die

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Corporate Office

Microchip Technology Inc. 2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 602 786-7200 Fax: 602 786-7277 *Technical Support:* 602 786-7627 *Web:* http://www.microchip.com/

Atlanta

Microchip Technology Inc. 500 Sugar Mill Road, Suite 200B Atlanta, GA 30350 Tel: 770 640-0034 Fax: 770 640-0307

Boston

Microchip Technology Inc. 5 Mount Royal Avenue Marlborough, MA 01752 Tel: 508 480-9990 Fax: 508 480-8575

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Dallas

Microchip Technology Inc. 14651 Dallas Parkway, Suite 816 Dallas, TX 75240-8809 Tel: 214 991-7177 Fax: 214 991-8588

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Microchip Technology Inc. Suite 150 Two Prestige Place Miamisburg, OH 45342 Tel: 513 291-1654 Fax: 513 291-9175

Los Angeles

Microchip Technology Inc. 18201 Von Karman, Suite 1090 Irvine, CA 92715 Tel: 714 263-1888 Fax: 714 263-1338

AMERICAS (continued) New York Microchip Technology Inc. 150 Motor Parkway, Suite 416 Hauppauge, NY 11788 Tel: 516 273-5305 Fax: 516 273-5335 San Jose Microchip Technology Inc. 2107 North First Street, Suite 590 San Jose, CA 95131 Tel: 408 436-7950 Fax: 408 436-7955 Toronto

Microchip Technology Inc. 5925 Airport Road, Suite 200 Mississauga, Ontario L4V 1W1, Canada Tel: 905 405-6279 Fax: 905 405-6253

ASIA/PACIFIC

Hong Kong

Microchip Technology Rm 3801B, Tower Two Metroplaza, 223 Hing Fong Road, Kwai Fong, N.T., Hong Kong Tel: 852 2 401 1200 Fax: 852 2 401 3431

Korea

Microchip Technology 168-1, Youngbo Bldg. 3 Floor Samsung-Dong, Kangnam-Ku, Seoul, Korea Tel: 82 2 554 7200 Fax: 82 2 558 5934 Singapore

Microchip Technology

200 Middle Road #10-03 Prime Centre Singapore 188980 Tel: 65 334 8870 Fax: 65 334 8850

Taiwan

Microchip Technology 10F-1C 207 Tung Hua North Road Taipei, Taiwan, ROC Tel: 886 2 717 7175 Fax: 886 2 545 0139

EUROPE

United Kingdom

Arizona Microchip Technology Ltd. Unit 6, The Courtyard Meadow Bank, Furlong Road Bourne End, Buckinghamshire SL8 5AJ Tel: 44 1 628 850303 Fax: 44 1 628 850178

France

Arizona Microchip Technology SARL Zone Industrielle de la Bonde 2 Rue du Buisson aux Fraises 91300 Massy - France Tel: 33 1 69 53 63 20 Fax: 33 1 69 30 90 79

Germany

Arizona Microchip Technology GmbH Gustav-Heinemann-Ring 125 D-81739 Muenchen, Germany Tel: 49 89 627 144 0 Fax: 49 89 627 144 44

Italy

Arizona Microchip Technology SRL Centro Direzionale Colleoni Palazzo Taurus 1 V. Le Colleoni 1 20041, Agrate Brianza, Milan Italy Tel: 39 39 689 9939 Fax: 39 39 689 9883

JAPAN

Microchip Technology Intl. Inc. Benex S-1 6F 3-18-20, Shin Yokohama Kohoku-Ku, Yokohama Kanagawa 222 Japan Tel: 81 45 471 6166 Fax: 81 45 471 6122

5/10/96



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